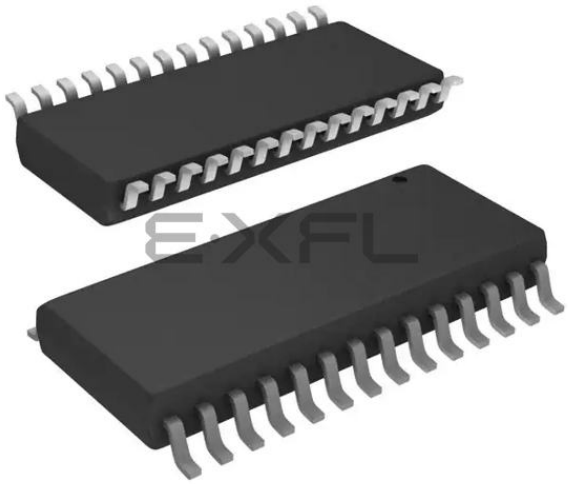

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

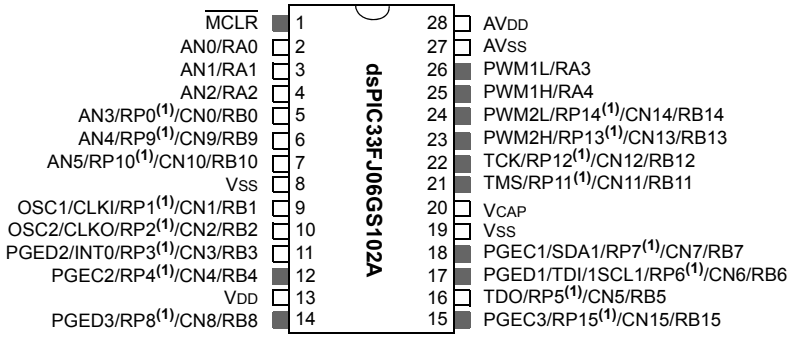
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	6KB (2K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b; D/A 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj06gs202a-e-so

Pin Diagrams (Continued)

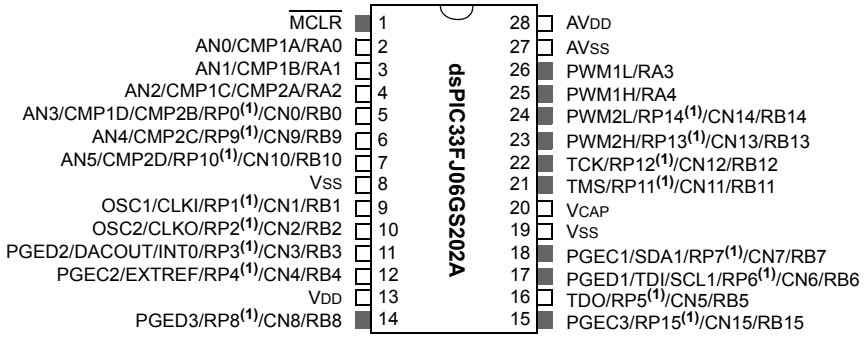
28-Pin SOIC, SPDIP, SSOP

■ = Pins are up to 5V tolerant



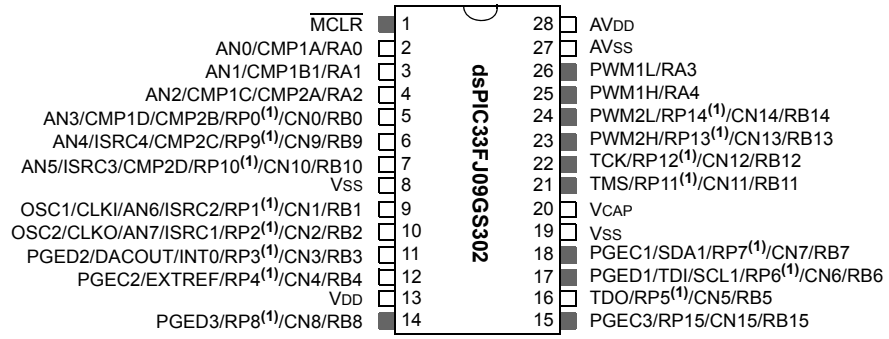
28-Pin SPDIP, SOIC, SSOP

■ = Pins are up to 5V tolerant



28-Pin SPDIP, SOIC, SSOP

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

4.5 Modulo Addressing

Modulo Addressing mode is a method used to provide an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either data or program space (since the data pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into program space) and Y data spaces. Modulo Addressing can operate on any W register pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can be configured to operate in only one direction as there are certain restrictions on the buffer start address (for incrementing buffers), or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers that have a power-of-two length. As these buffers satisfy the start and end address criteria, they can operate in a bidirectional mode (that is, address boundary checks are performed on both the lower and upper address boundaries).

4.5.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-1).

Note:	Y space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

4.5.2 W ADDRESS REGISTER SELECTION

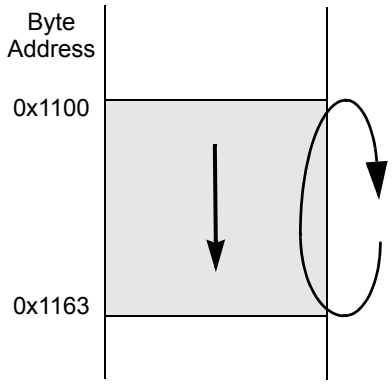
The Modulo and Bit-Reversed Addressing Control register, MODCON<15:0>, contains enable flags as well as a W register field to specify the W Address registers. The XWM and YWM fields select the registers that will operate with Modulo Addressing:

- If XWM = 15, X RAGU and X WAGU Modulo Addressing is disabled
- If YWM = 15, Y AGU Modulo Addressing is disabled

The X Address Space Pointer W register (XWM), to which Modulo Addressing is to be applied, is stored in MODCON<3:0> (see Table 4-1). Modulo Addressing is enabled for X data space when XWM is set to any value other than '15' and the XMODEN bit is set at MODCON<15>.

The Y Address Space Pointer W register (YWM) to which Modulo Addressing is to be applied is stored in MODCON<7:4>. Modulo Addressing is enabled for Y data space when YWM is set to any value other than '15' and the YMODEN bit is set at MODCON<14>.

FIGURE 4-6: MODULO ADDRESSING OPERATION EXAMPLE




```
MOV     #0x1100, W0
MOV     W0, XMODSRT     ;set modulo start address
MOV     #0x1163, W0
MOV     W0, MODEND      ;set modulo end address
MOV     #0x8001, W0
MOV     W0, MODCON      ;enable W1, X AGU for modulo

MOV     #0x0000, W0     ;W0 holds buffer fill value

MOV     #0x1110, W1     ;point W1 to buffer

DO      AGAIN, #0x31    ;fill the 50 buffer locations
MOV     W0, [W1++]      ;fill the next location
AGAIN:  INC W0, W0      ;increment the fill value
```

REGISTER 5-2: NVMKEY: NONVOLATILE MEMORY KEY REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
NVMKEY<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMKEY<7:0>:** Key Register bits (write-only)

6.1 Reset Control Register

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1)

R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	—	—	—	—	CM	VREGS
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR	SWR	SWDTEN(2)	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or uninitialized W Reset has not occurred

bit 13-10 **Unimplemented:** Read as '0'

bit 9 **CM:** Configuration Mismatch Flag bit
1 = A Configuration Mismatch Reset has occurred
0 = A Configuration Mismatch Reset has NOT occurred

bit 8 **VREGS:** Voltage Regulator Standby During Sleep bit
1 = Voltage regulator is active during Sleep
0 = Voltage regulator goes into Standby mode during Sleep

bit 7 **EXTR:** External Reset Pin ($\overline{\text{MCLR}}$) bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset Flag (Instruction) bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(2)
1 = WDT is enabled
0 = WDT is disabled

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

bit 3 **SLEEP:** Wake-up from Sleep Flag bit
1 = Device has been in Sleep mode
0 = Device has not been in Sleep mode

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 7-21: IPC2: INTERRUPT PRIORITY CONTROL REGISTER 2

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U1RXIP<2:0>(1)			—	SPI1IP<2:0>(1)		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	SPI1EIP<2:0>(1)			—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **U1RXIP<2:0>:** UART1 Receiver Interrupt Priority bits(1)
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **SPI1IP<2:0>:** SPI1 Event Interrupt Priority bits(1)
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **SPI1EIP<2:0>:** SPI1 Error Interrupt Priority bits(1)
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

Note 1: These bits are not implemented in the dsPIC33FJ06GS001 device.

REGISTER 7-24: IPC5: INTERRUPT PRIORITY CONTROL REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	INT1IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-3 **Unimplemented:** Read as '0'

bit 2-0 **INT1IP<2:0>:** External Interrupt 1 Priority bits

111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 7-25: IPC7: INTERRUPT PRIORITY CONTROL REGISTER 7

U-0	U-1	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	INT2IP<2:0>			—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **INT2IP<2:0>:** External Interrupt 2 Priority bits

111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 8-4: OSCTUN: FRC OSCILLATOR TUNING REGISTER(2)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TUN<5:0>(1)					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **TUN<5:0>:** FRC Oscillator Tuning bits(1)

011111 = Center frequency + 11.625% (8.23 MHz)
011110 = Center frequency + 11.25% (8.20 MHz)
•
•
•
000001 = Center frequency + 0.375% (7.40 MHz)
000000 = Center frequency (7.37 MHz nominal)
111111 = Center frequency – 0.375% (7.345 MHz)
•
•
•
100001 = Center frequency – 11.625% (6.52 MHz)
100000 = Center frequency – 12% (6.49 MHz)

Note 1: OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation and is neither characterized nor tested.

2: This register is reset only on a Power-on Reset (POR).

13.1 Input Capture Registers

REGISTER 13-1: IC1CON: INPUT CAPTURE 1 CONTROL REGISTER

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	ICSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-0, HC	R-0, HC	R/W-0	R/W-0	R/W-0
ICTMR(1)	ICI<1:0>		ICOV	ICBNE	ICM<2:0>		
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **ICSIDL:** Input Capture Module Stop in Idle Control bit
1 = Input capture module halts in CPU Idle mode
0 = Input capture module continues to operate in CPU Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **ICTMR:** Input Capture Timer Select bit(1)
1 = TMR2 contents are captured on capture event
0 = Reserved

bit 6-5 **ICI<1:0>:** Select Number of Captures per Interrupt bits
11 = Interrupt on every fourth capture event
10 = Interrupt on every third capture event
01 = Interrupt on every second capture event
00 = Interrupt on every capture event

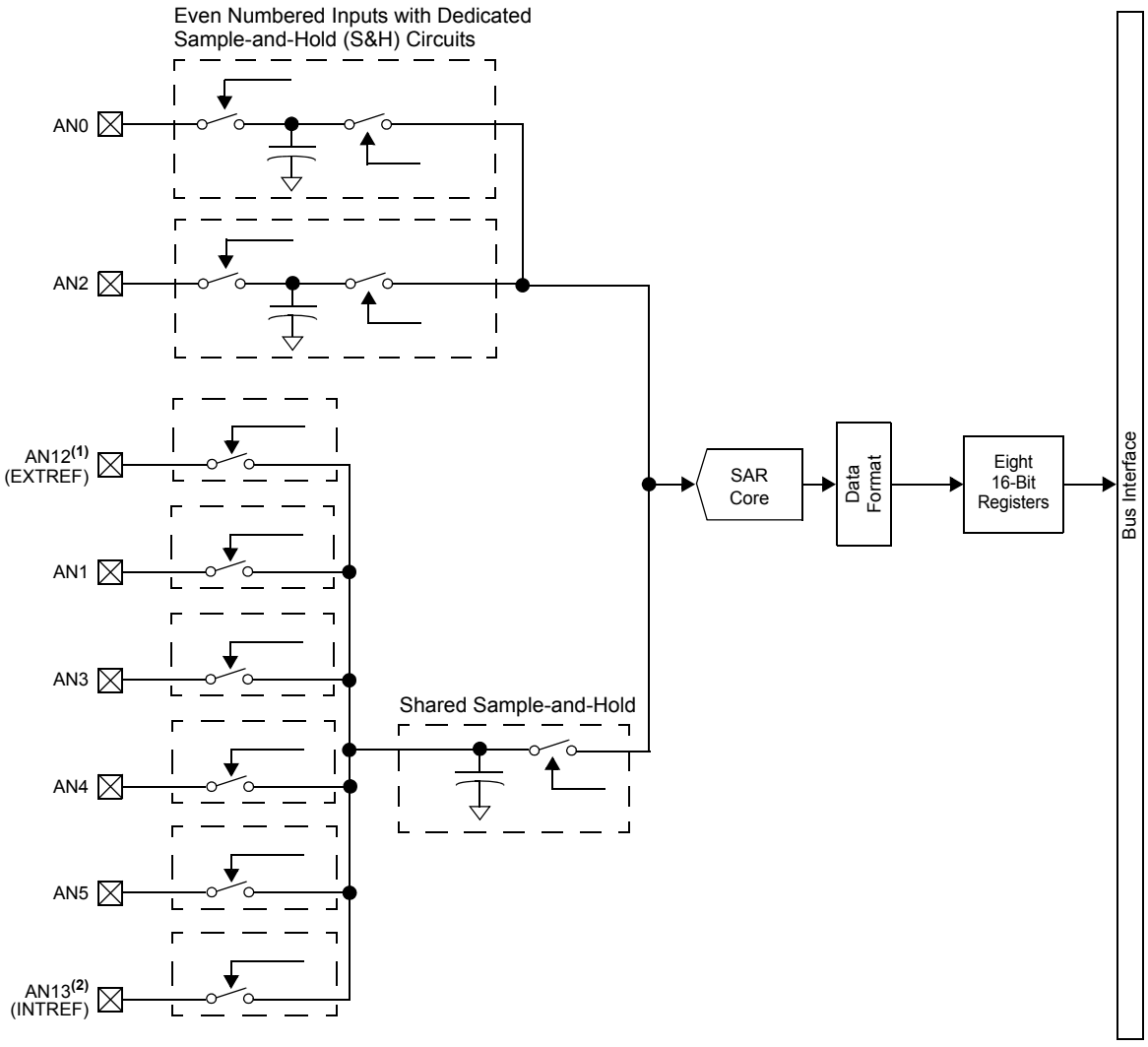
bit 4 **ICOV:** Input Capture Overflow Status Flag bit (read-only)
1 = Input capture overflow occurred
0 = No input capture overflow occurred

bit 3 **ICBNE:** Input Capture Buffer Empty Status bit (read-only)
1 = Input capture buffer is not empty, at least one more capture value can be read
0 = Input capture buffer is empty

bit 2-0 **ICM<2:0>:** Input Capture Mode Select bits
111 = Input capture functions as interrupt pin only when device is in Sleep or Idle mode. Rising edge detect only; all other control bits are not applicable.
110 = Unused (module disabled)
101 = Capture mode, every 16th rising edge
100 = Capture mode, every 4th rising edge
011 = Capture mode, every rising edge
010 = Capture mode, every falling edge
001 = Capture mode, every edge (rising and falling). ICI<1:0> bits do not control interrupt generation for this mode.
000 = Input capture module is turned off

Note 1: This bit is not available in dsPIC33FJ06GS001/101A/102A devices.

FIGURE 19-4: ADC BLOCK DIAGRAM FOR dsPIC33FJ06GS202A DEVICE



Note 1: To measure the voltage at AN12 (EXTREF), an analog comparator must be enabled and EXTREF must be selected as the comparator reference.

2: AN13 (INTREF) is an internal analog input and is not available on a pin.

NOTES:

REGISTER 20-2: CMPDACx: COMPARATOR DAC CONTROL x REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	CMREF<9:8>(1)	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CMREF<7:0>(1)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9-0 **CMREF<9:0>:** Comparator Reference Voltage Select bits(1)

1111111111 = (CMREF * INTREF/1024) or (CMREF * (AVDD/2)/1024) volts depending on RANGE bit or (CMREF * EXTREF/1024) if EXTREF is set

•

•

•

0000000000 = 0.0 volts

Note 1: These bits are not implemented in dsPIC33FJ06GS101A/102A devices.

22.0 SPECIAL FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. "Programming and Diagnostics"** (DS70207) and **Section 25. "Device Configuration"** (DS70194) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ06GS001/101A/102A/202A and dsPIC33FJ09GS302 family of devices includes several features that are included to maximize application flexibility and reliability, and minimize cost through elimination of external components. These features are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation
- Brown-out Reset (BOR)

22.1 Configuration Bits

The configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in the words at the top of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 22-1 and Table 22-2. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration byte for configuration data. This is to make certain that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '1111 1111 1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

Note: Performing a page erase operation on the last page of program memory, clears the Flash Configuration Words, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory

The Configuration Flash Byte maps are shown in Table 22-1 and Table 22-2.

The Constant Current Source Calibration register is shown in Register 22-1.

TABLE 22-3: dsPIC33F CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Description
PLLKEN	PLL Lock Enable bit 1 = Clock switch to PLL source will wait until the PLL lock signal is valid 0 = Clock switch will not wait for the PLL lock signal
JTAGEN	JTAG Enable bit 1 = JTAG is enabled 0 = JTAG is disabled
ICS<1:0>	ICD Communication Channel Select bits 11 = Communicate on PGEC1 and PGED1 10 = Communicate on PGEC2 and PGED2 01 = Communicate on PGEC3 and PGED3 00 = Reserved, do not use

24.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

24.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

24.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

24.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

TABLE 25-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	**Typical(1)**	**Max.**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off Clock On Base Current(2)						
DC40d	13	21	mA	-40°C	3.3V	10 MIPS
DC40a	13	21	mA	+25°C		
DC40b	13	21	mA	+85°C		
DC40c	13	21	mA	+125°C		
DC41d	16	24	mA	-40°C	3.3V	16 MIPS(3)
DC41a	16	24	mA	+25°C		
DC41b	16	24	mA	+85°C		
DC41c	16	24	mA	+125°C		
DC42d	17	27	mA	-40°C	3.3V	20 MIPS(3)
DC42a	17	27	mA	+25°C		
DC42b	17	27	mA	+85°C		
DC42c	17	27	mA	+125°C		
DC43d	20	32	mA	-40°C	3.3V	30 MIPS(3)
DC43a	20	32	mA	+25°C		
DC43b	20	32	mA	+85°C		
DC43c	20	32	mA	+125°C		
DC44d	23	37	mA	-40°C	3.3V	40 MIPS
DC44a	23	37	mA	+25°C		
DC44b	23	37	mA	+85°C		
DC44c	23	37	mA	+125°C		

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

2: Base Idle current is measured as follows:

- CPU core is off, oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD; WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)

3: These parameters are characterized but not tested in manufacturing.

TABLE 25-8: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

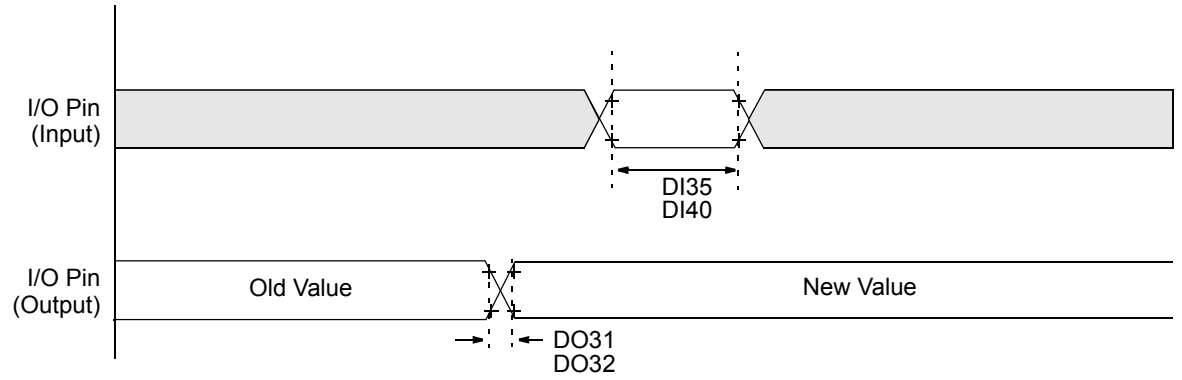
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Typical(1)**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (IDOZE)(2)							
DC73a	30	45	1:2	mA	-40°C	3.3V	40 MIPS
DC73f	16	23	1:64	mA			
DC73g	16	23	1:128	mA			
DC70a	30	45	1:2	mA	+25°C	3.3V	40 MIPS
DC70f	16	23	1:64	mA			
DC70g	16	23	1:128	mA			
DC71a	30	45	1:2	mA	+85°C	3.3V	40 MIPS
DC71f	16	23	1:64	mA			
DC71g	16	23	1:128	mA			
DC72a	30	45	1:2	mA	+125°C	3.3V	40 MIPS
DC72f	16	23	1:64	mA			
DC72g	16	23	1:128	mA			

Note 1: Data in the Typical column is at 3.3V, +25°C unless otherwise stated.

2: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD; WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)
- CPU is executing `while(1)` statement

FIGURE 25-3: I/O TIMING CHARACTERISTICS



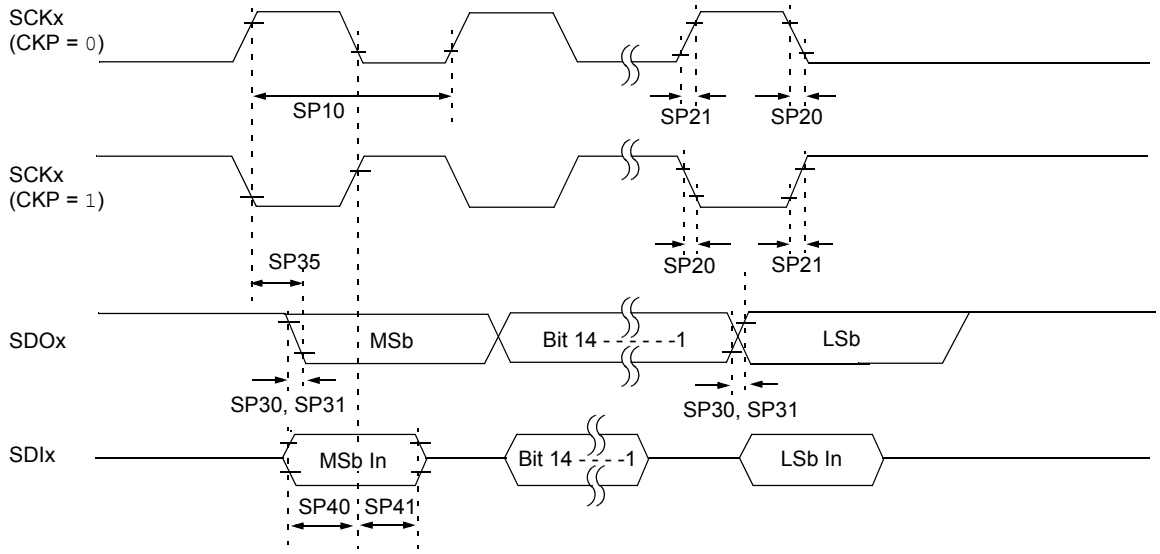
Note: Refer to Figure 25-1 for load conditions.

TABLE 25-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	I/O Pins: 4x Sink Driver Pins RA0-RA2, RB0-RB2, RB5-RB10, RB15	—	10	25	ns	Refer to Figure 25-1 for test conditions
		I/O Pins: 16x Sink Driver Pins RA3, RA4, RB3, RB4, RB11-RB14	—	6	15	ns	
DO32	TIOF	I/O Pins: 4x Sink Driver Pins RA0-RA2, RB0-RB2, RB5-RB10, RB15	—	10	25	ns	Refer to Figure 25-1 for test conditions
		I/O Pins: 16x Sink Driver Pins RA3, RA4, RB3, RB4, RB11-RB14	—	6	15	ns	
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

FIGURE 25-14: SPIx MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 25-1 for load conditions.

TABLE 25-32: SPIx MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCKx Frequency	—	—	9	MHz	-40ºC to +125ºC and see **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 111 ns. The clock generated in master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-9: TYPICAL FRC FREQUENCY @ VDD = 3.3V

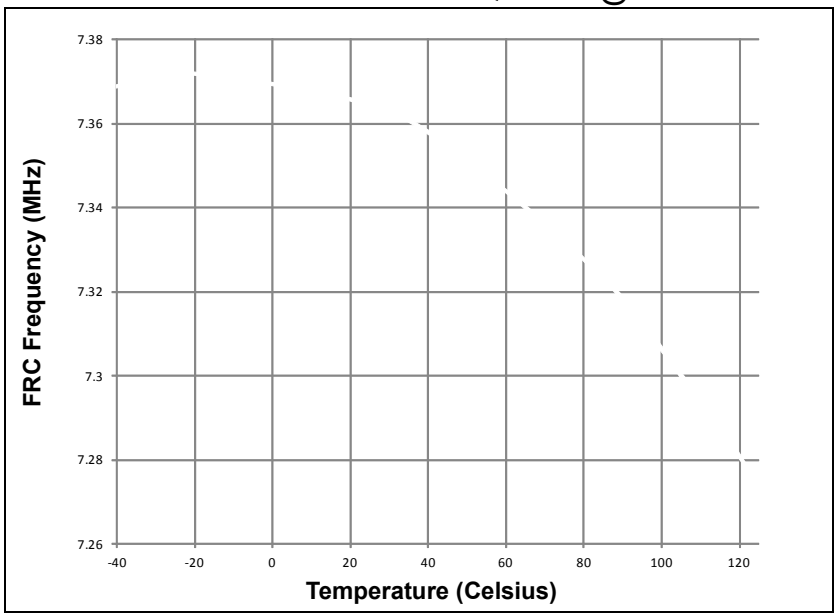


FIGURE 26-10: TYPICAL INTREF @ VDD = 3.3V

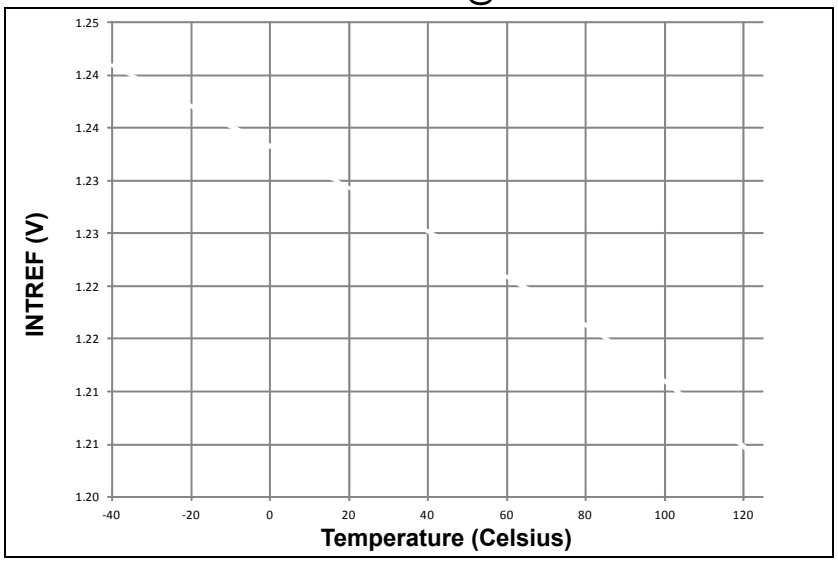
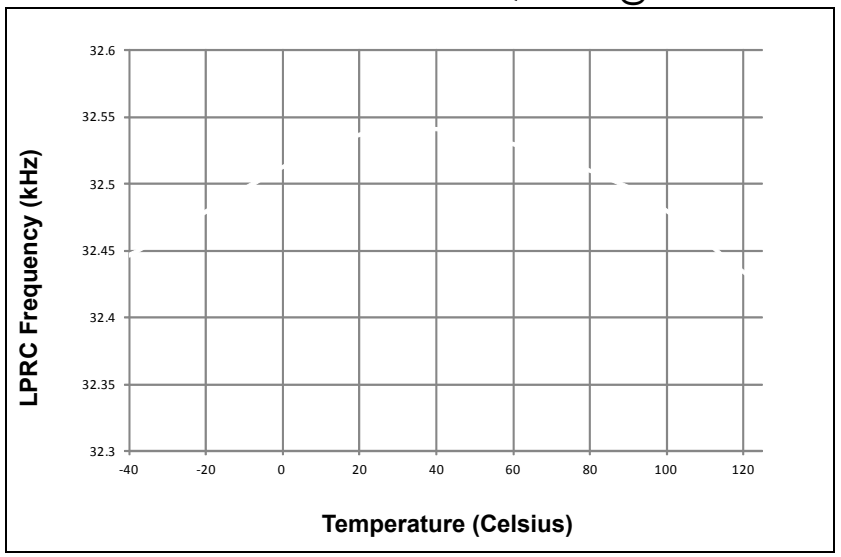


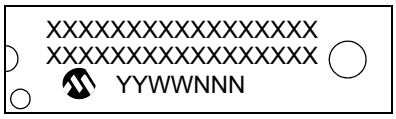
FIGURE 26-11: TYPICAL LPRC FREQUENCY @ VDD = 3.3V



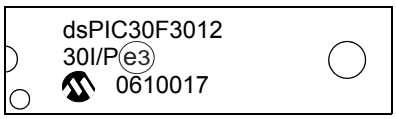
27.0 PACKAGING INFORMATION

27.1 Package Marking Information

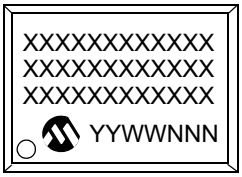
18-Lead PDIP



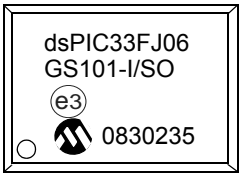
Example



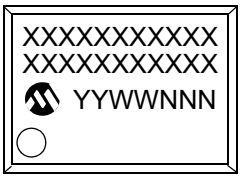
18-Lead SOIC (.300”)



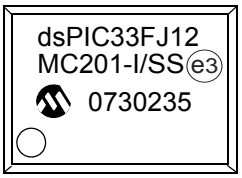
Example



20-Lead SSOP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.